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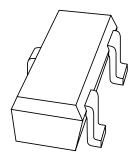
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **2PB709A**PNP general purpose transistor

Product data sheet Supersedes data of 1997 Jun 19 1999 Apr 23



# PNP general purpose transistor

2PB709A

#### **FEATURES**

• Low current (max. 100 mA)

• Low voltage (max. 45 V).

#### **APPLICATIONS**

• General purpose switching and amplification.

#### **DESCRIPTION**

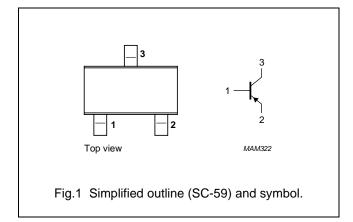
PNP transistor in an SC-59 plastic package. NPN complement: 2PB601A.

#### **MARKING**

TYPE NUMBER	MARKING CODE
2PB709AQ	BQ
2PB709AR	BR
2PB709AS	BS

#### **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-45	V
$V_{CEO}$	collector-emitter voltage	open base	_	-45	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-6	V
I <sub>C</sub>	collector current (DC)		_	-100	mA
I <sub>CM</sub>	peak collector current		_	-200	mA
I <sub>BM</sub>	peak base current		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

# PNP general purpose transistor

2PB709A

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = -45 V	_	-10	nA
		$I_E = 0$ ; $V_{CB} = -45 \text{ V}$ ; $T_j = 150 ^{\circ}\text{C}$	_	-5	μА
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = -5 V	_	-10	nA
h <sub>FE</sub>	DC current gain	$I_C = -2 \text{ mA}; V_{CE} = -10 \text{ V}$			
	2PB709AQ		160	260	
	2PB709AR		210	340	
	2PB709AS		290	460	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -100 \text{ mA}$ ; $I_B = -10 \text{ mA}$ ; note 1	_	-500	mV
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	5	pF
f <sub>T</sub>	transition frequency	$I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}; f = 100 \text{ MHz}$			
	2PB709AQ		60	_	MHz
	2PB709AR		70	_	MHz
	2PB709AS		80	_	MHz

#### Note

1. Pulse test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

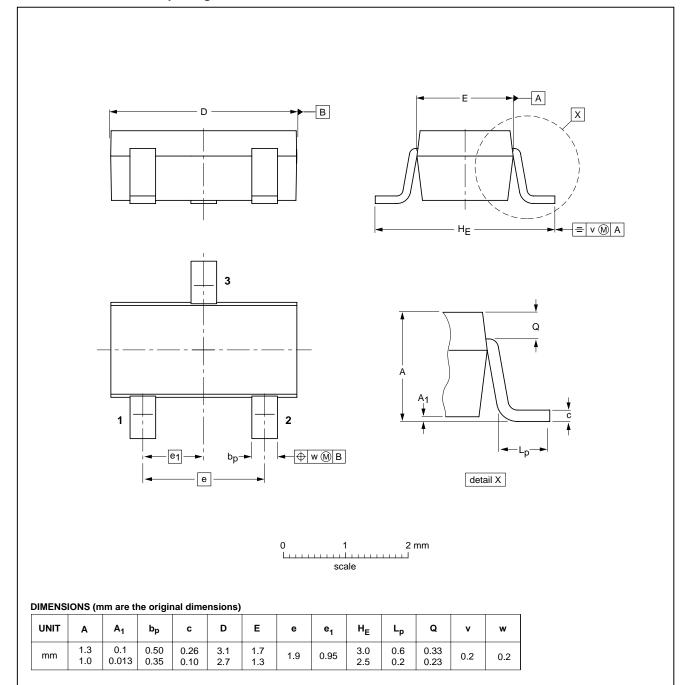
# PNP general purpose transistor

2PB709A

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT346** 



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT346		TO-236	SC-59			98-07-17

### PNP general purpose transistor

2PB709A

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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# **NXP Semiconductors**

#### **Customer notification**

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#### **Contact information**

For additional information please visit:  $\label{eq:http://www.nxp.com} \textbf{For additional information please visit: } \textbf{http://www.nxp.com}$ 

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